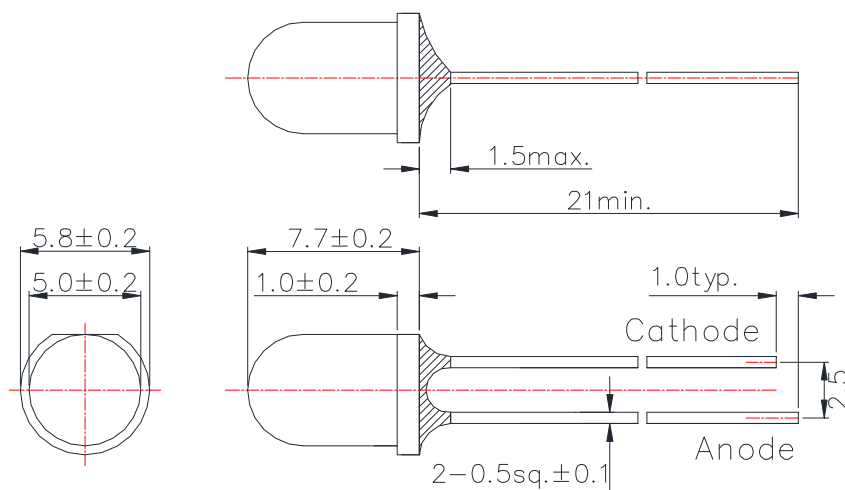


**PRELIMINARY**

PDO10-04

Mold type PIN-Photodiode

Outline and Internal Circuit



(Unit : mm)

Features

- Chip Material : Si
- Chip Dimension : 1000um * 1000um
- Active Area : 800um * 800um
- Number of Chips : 1pce
- Package Type : $\phi 5\text{mm}$ clear molding
- Lead Frame : Soldered (Lead Free)
- Lens : Epoxy Resin

Application

Absolute Maximum Ratings (Tc=25°C)

Item	Symbol	Ratings	Unit
Reverse Breakdown Voltage	VR	170	V
Operating Temperature	Topr	-25 ~ +100	°C
Storage Temperature	Tstg	-30 ~ +100	°C
Soldering Temperature	TSOL	265	°C

‡Soldering condition : Soldering condition must be completed with 3 seconds at 265°C.

Optical and Electrical Characteristics (Tc=25°C)

(*: 100% testing, **: reference value)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Photo Current	IL		20		uA	VR=10V**
Dark Current	ID			1	uA	VR=10V*
Open Circuit Voltage	VOC		410		mV	VR=0V**
Spectral Responsivity (Peak)	λ_p		900		nm	VR=10V**
Viewing Half Angle	$\theta_{1/2}$		±45		deg.	VR=0V**
Total Capacitance	CT		21		pF	VR=5V f=1MHz**
Rise Time	tr		10		ns	VR=0V RL=1MΩ**
Fall Time	tf		10		ns	VR=0V RL=1MΩ**

‡ Measured by USHIO's calibrated tool.

Disclaimer

Product specifications and data shown in this product catalog are subject to change without notice for the purposes of improving product performance, reliability, design, or otherwise.

Product data and parameters in this catalog are typical values based on reasonably up-to-date measurements.

Product data and parameters may vary by user application and over time.

Products shown in this catalog are intended to be used for general electronic equipment. Products are not guaranteed for applications where product malfunction or failure may cause personal injury or death, including but not limited to life-supporting / saving devices, medical devices, safety devices, airplanes, aerospace equipment, automobiles, traffic control systems, and nuclear reactor control systems.